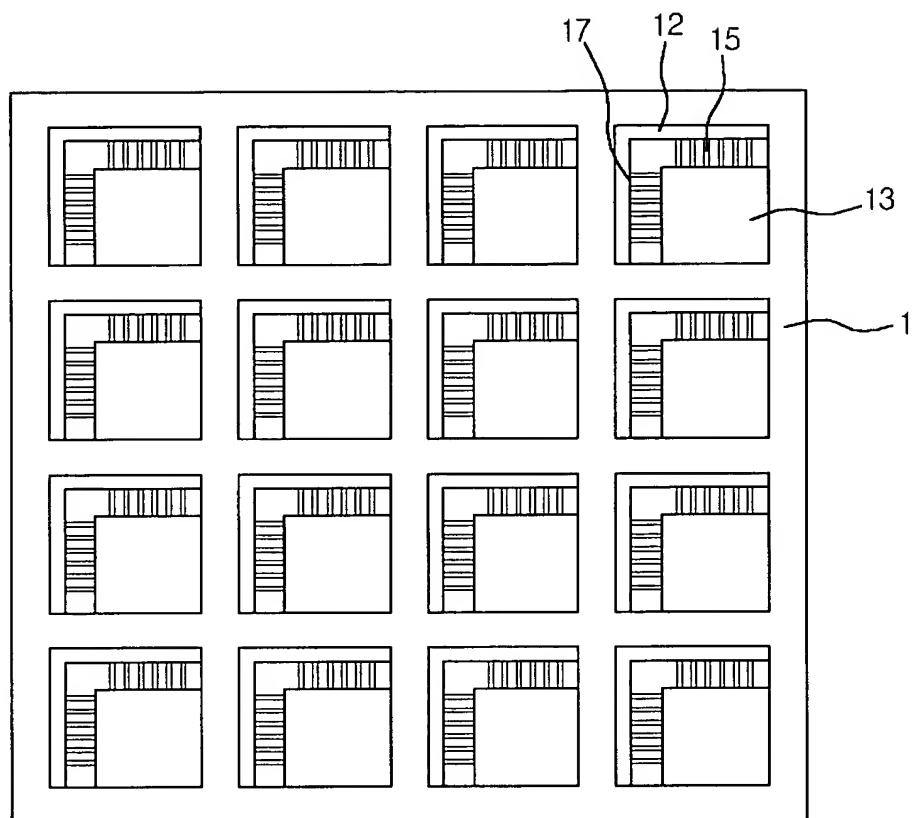


Fig.1
Related Art



The diagram illustrates a cross-section of a complex electronic substrate. At the top, a thin layer (1) contains a patterned conductive surface (6). Beneath this is a thick central core (2), which houses multiple horizontal conductive layers (10) separated by insulating material. Vertical vias (11) connect these internal layers to the top and bottom surfaces. On the left side, there is a vertical stack of materials, possibly a heat sink or mounting base, with additional conductive features (17) and vias (11) connecting it to the main substrate layers. The bottom of the assembly consists of another thin layer (3). Two circular regions, A and B, are indicated with dashed lines, likely representing areas of interest or specific manufacturing details.

Fig.3A
Related Art

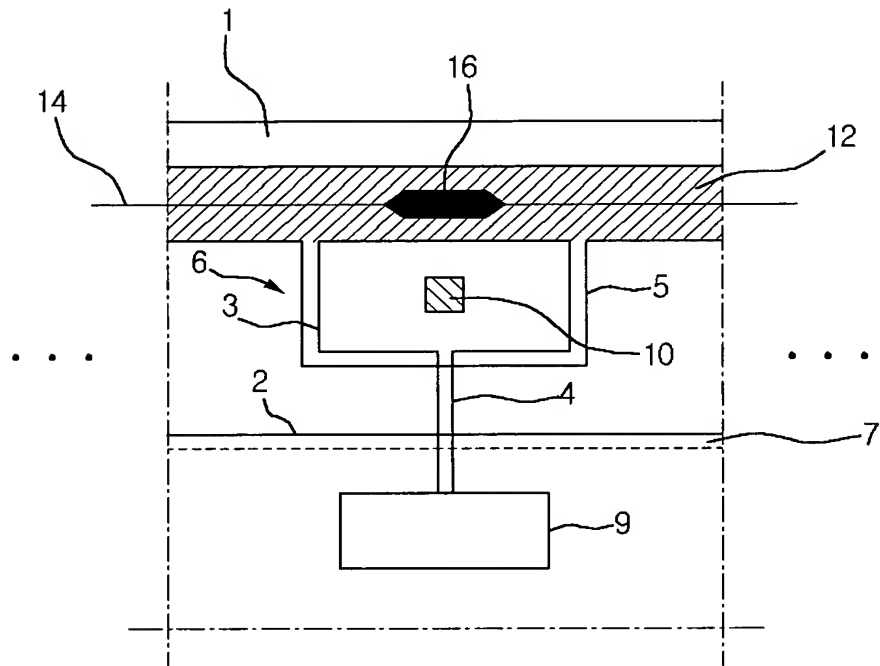


Fig.3B
Related Art

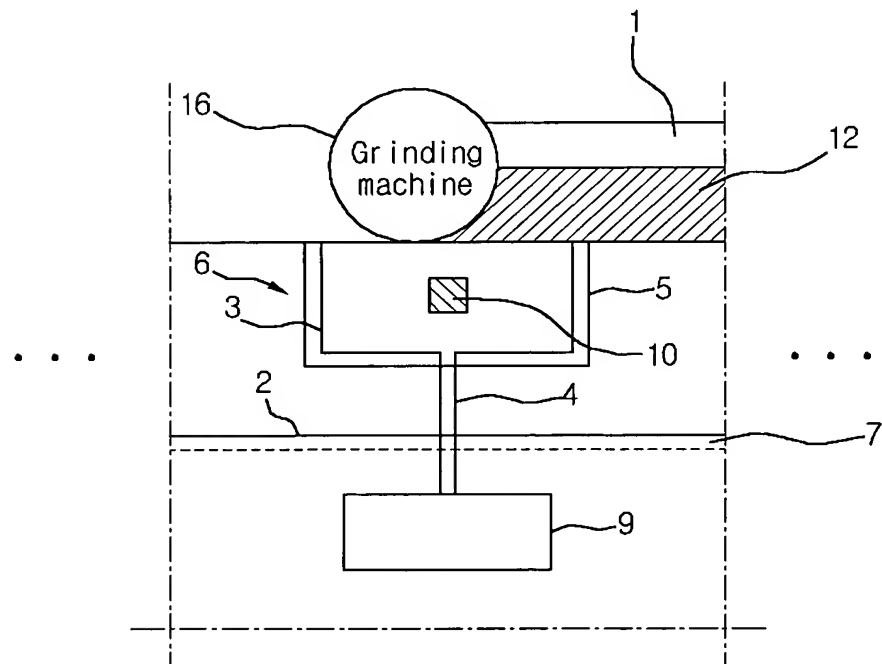


Fig.3C
Related Art

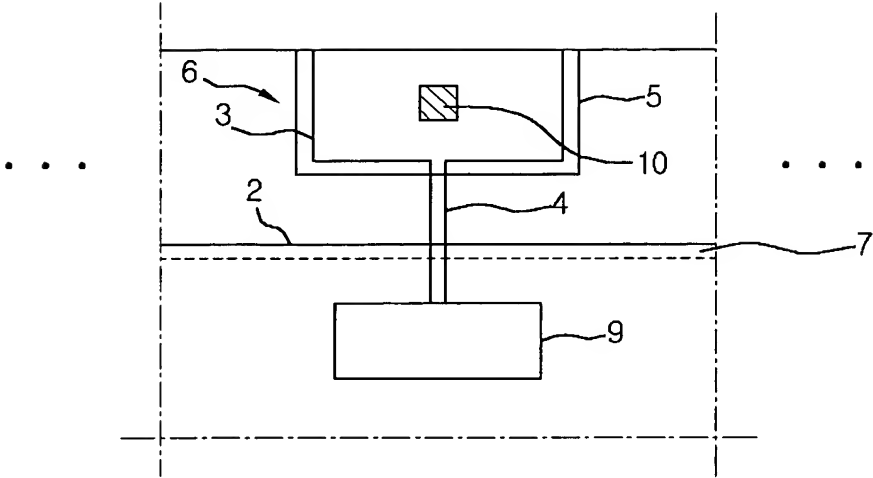


Fig.4A

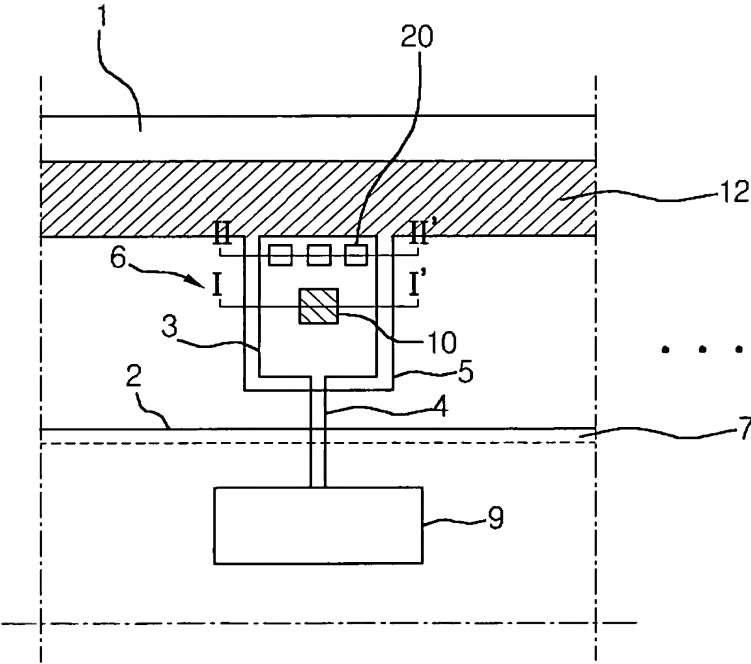


Fig.4B

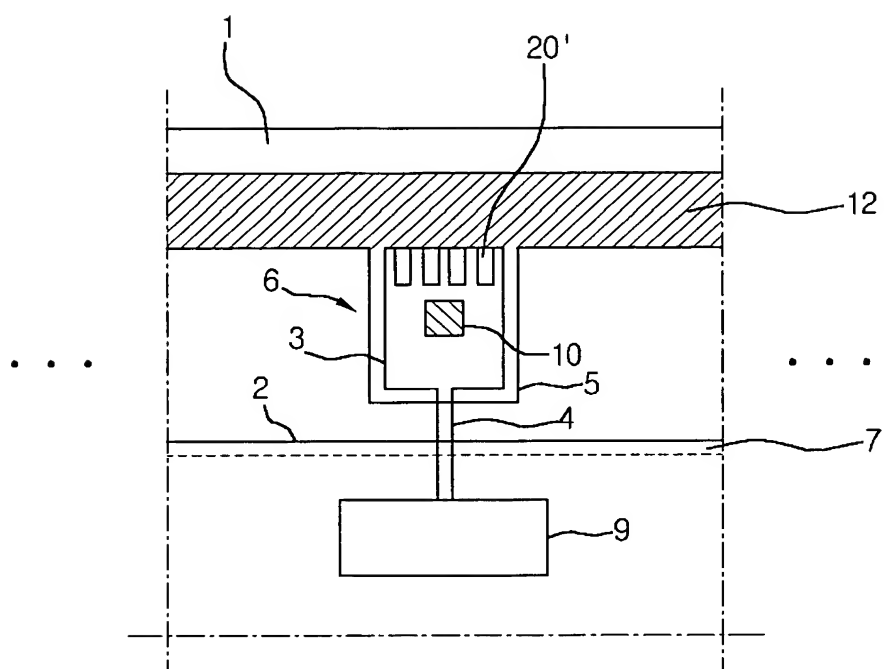


Fig.5A

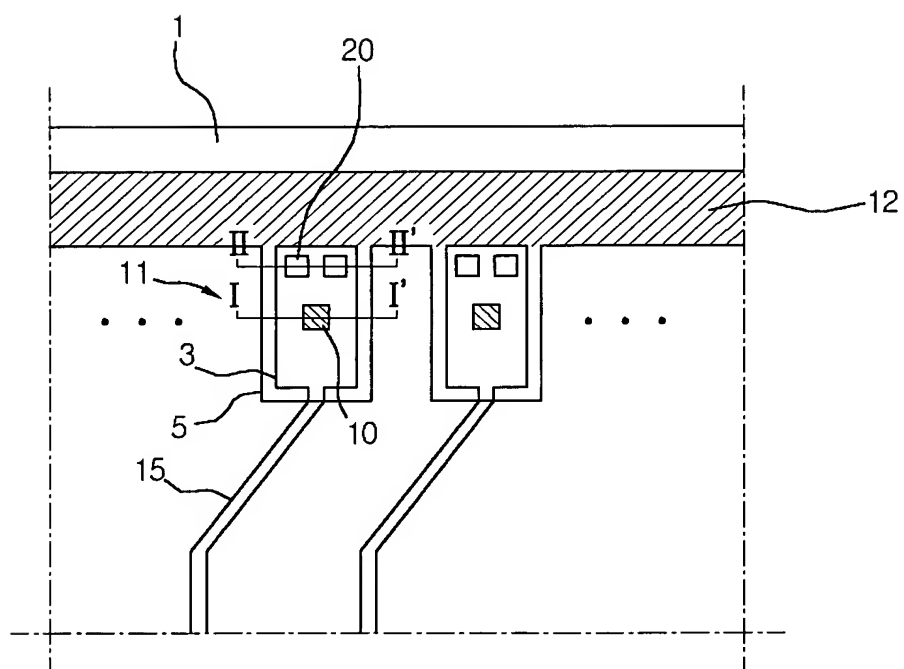


Fig.5B

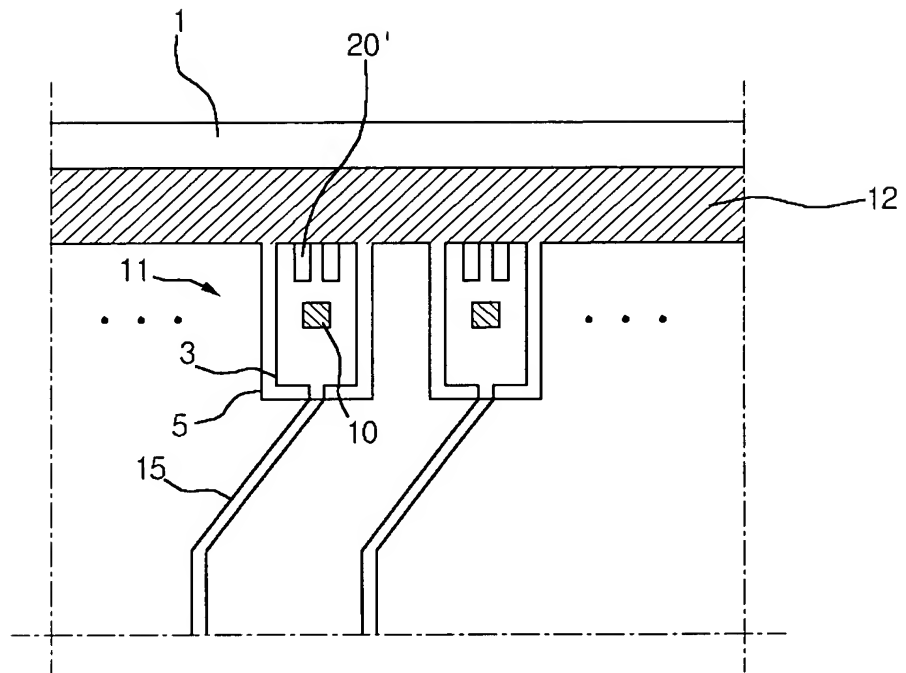


Fig.6A

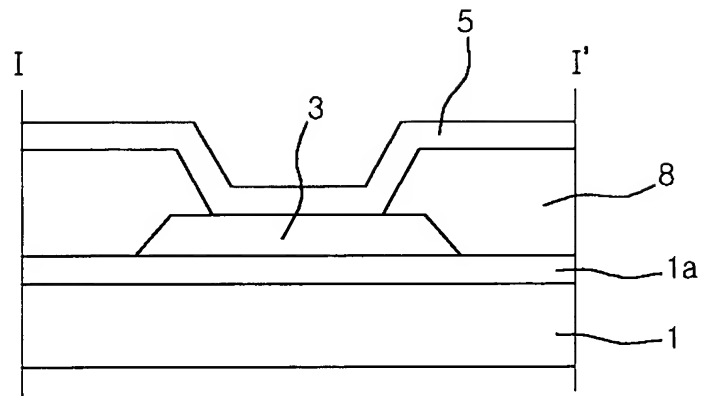


Fig.6B

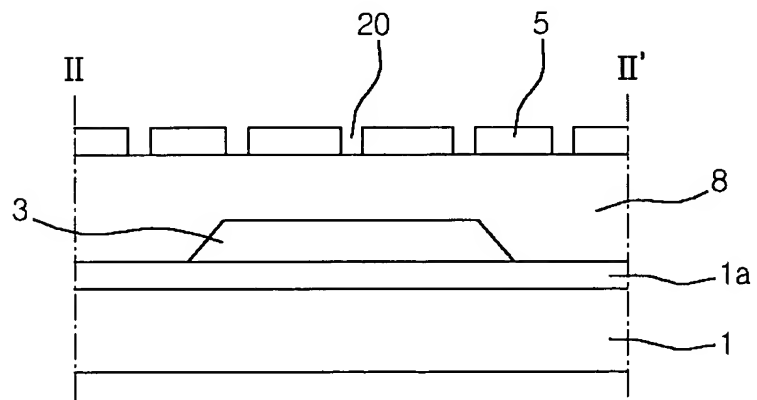


Fig.7A

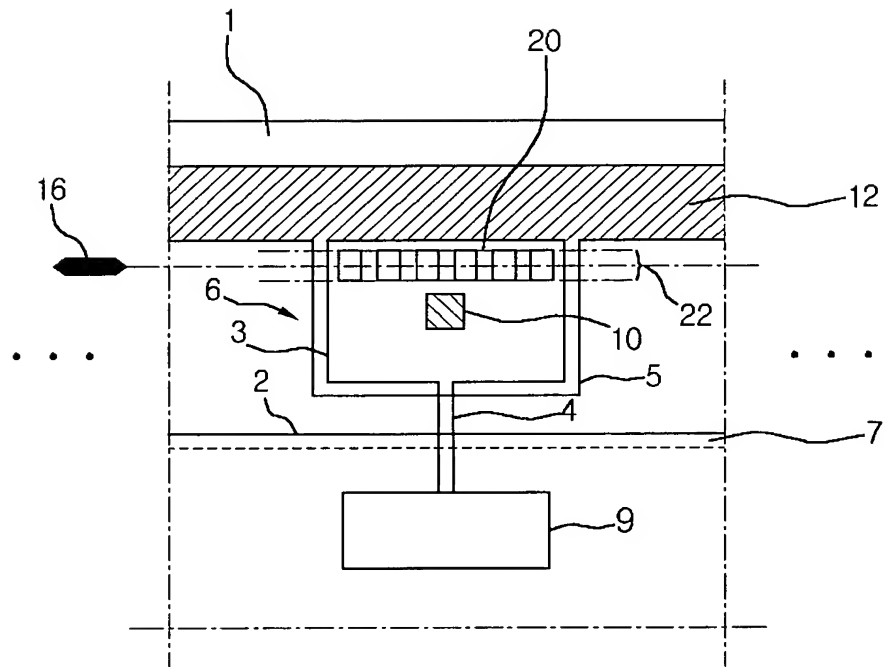


Fig.7B

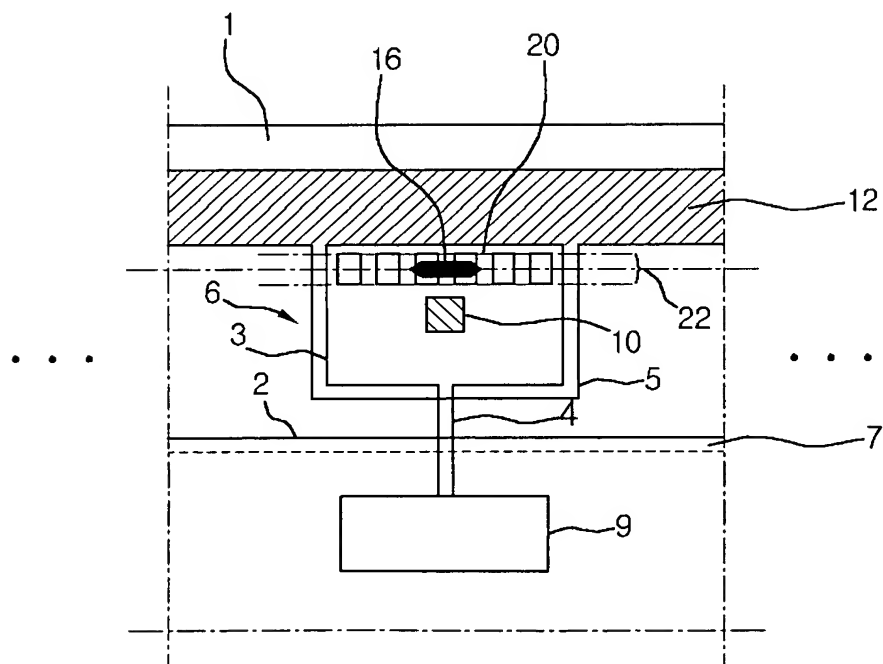


Fig.7C

